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gray scale levels, and the optical density of the darkest gray scale level not exceeding the optical density of the uniformly darkened portion of the LDW-glass.

Cancel Claims 1-20 without prejudice.

REMARKS

New Claims 21-44 are in the application; original Claims 1-20 having been canceled without prejudice. New Claims 21-44 are supported by the specification as filed and add no new matter to the application.

The Examiner objected to original Claims 1-20 on a number of grounds which are set forth in the Action. The Examiner objected to the claims under 37 CFR 1.75(c) as set forth on page 3 of the action and rejected all the claims under 35 USC Section 112, second paragraph, as set forth in pages 3-10 of the Action. Rather than amending the claims to overcome the objections and rejections, applicant has found it more efficient to replace the original claims with the new claims which Applicants submit fully comply with the rules and regulations, and obviates the Examiner's objections and rejection of the original claims.

Claims 21 through 30 are based on the original Claims 1-6. New Claims 31-44 are based on original Claims 11-19. Applicant will file a continuation application to pick up the subject matter of original Claims 7-10.

Claims 21 and 22 are directed to a gray scale mask and Claim 23 is directed to a method of making a gray scale mask. These claims are based on original Claims 1 and 2. Claim 24 is directed to a method of making a three dimensional microstructure with three dimensional surfaces in a photoresist and Claim 25 is directed to analog photoresist with three dimensional microstructure produced by the process as set forth

in the claim. These two claims are based on original Claim 4. Claim 26 is directed to a method of producing three dimensional microstructures in substrate material and is based on original Claim 4. Claim 27 is directed to a component having a three dimensional microstructure produced by the process set forth in the claim. Claim 29 is directed to a method for producing a component having a three dimensional microstructure. These two claims are based on original Claim 5. Claim 28 is directed to a component having a three dimensional microstructure selected from a group of components which are produced by the method set forth in the claim, and Claim 30 is directed to a method of producing a component having a three dimensional microstructure selected from the group of components set forth in the claim. These two claims are based on original Claim 6.

Claims 31 is directed to a laser direct write-glass and is based on original Claims 11 and 16. Claims 32 and 33 are directed to gray scale mask produced by the process set forth in the claim. These two claims are based on original Claim 16. Claims 34-37 are directed to the method of making a gray scale mask and are based on original Claim 11. Claim 38 is directed to a method of making a three dimensional microstructure with three dimensional surfaces according to the process set forth in the claim. Claim 38 is based on original Claim 12-17. Claim 39 is directed to analog photoresist with three dimensional microstructure produced by the process set forth in the claim and Claim 40 is directed to a method of producing three dimensional microstructure in a substrate material. Claims 39 and 40 are based on Claims 13 and 18. Claim 41 is directed to a component having a three dimensional microstructure selected from the group set forth in the claim and produced by the process set forth in the claim. Claim 43 is directed to a method of producing a component having a three dimensional microstructure selected

from the group set forth in the claim. Claims 41 and 43 are based on original Claims 14 and 18. Claim 42 is directed to a component having a three dimensional microstructure selected from the group set forth in the claim and produced by the process set forth in the claim and Claim 44 is directed to a method of producing a component having a three dimensional microstructure selected from the group as set forth in the claim. These claims are based on original Claims 15 and 19.

It is respectfully submitted that the new claims are fully supported by the specification as filed and add no new matter to the application. It is further submitted that the new claims do not necessitate an additional search by the Examiner.

In light of the fact the new claims were added to replaced original Claims 1-20 to overcome the numerous objections and rejections set forth in the Action. It is respectfully submitted that the new claims obviate these objections and rejections.

The original claims were rejected under 35 USC 103(a) in view of the Applicant's five earlier U.S. patents identified in the Action (the Wu Patent). As pointed out by the Examiner, these earlier patents disclose the HEBS-glass; however, the new claims do not claim HEBS-glass, they claim products derived from HEBS-glass, other products which are produced using the products derived from HEBS-glass, methods for making the products derived from HEBS-glass. The claimed inventions are not disclosed in the Wu patents and are not obvious in view of the teaching of the five cited Wu patents. It would not have been obvious to one with ordinary skill in the art to take the teaching of the Wu patents to make the claimed invention. The prior art must have some suggestion or teaching to direct one ordinary skilled in the art to modify the prior art to obtain the claimed invention. Wu does not teach producing gray scales from

HEBS-glass, does not teach employing a gray scale made from HEBS-glass to produce a three dimensional microstructure, a method of transferring the microstructure to a substrate, and/or components having a substrate with a three dimensional structure.

In light of the amendment and remarks, Applicants respectfully request allowance of the new claims.

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Respectfully submitted,

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